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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Keep safety first in your circuit designs!

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HRW0202B

Silicon Schottky Barrier Diode for Rectifying

RENESAS

ADE-208-345A (Z)

Rev. 1
Oct. 1997

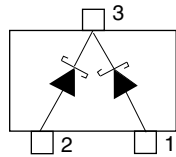
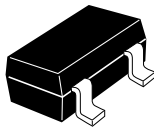
Features

- Low forward voltage drop and suitable for high efficiency rectifying.
- MPAK Package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HRW0202B	S18	MPAK

Pin Arrangement



(Top View)

- 1 Anode
- 2 Anode
- 3 Cathode

Absolute Maximum Ratings ^{*1}

(Ta = 25°C)

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}^{*2}	20	V
Average rectified current	I_O^{*2}	200	mA
Non-Repetitive peak forward surge current	I_{FSM}^{*3}	3	A
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Notes 1. Two device total

Notes 2. See from Fig.4 to Fig.7

Notes 3. 10ms sine wave 1 pulse

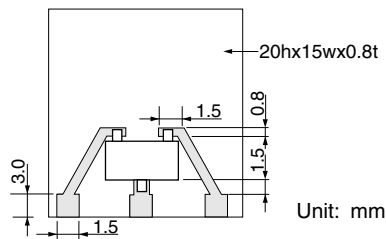
Electrical Characteristics ^{*1}

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_F	—	—	0.42	V	$I_F = 100 \text{ mA}$
Reverse current	I_R	—	—	10	μA	$V_R = 20\text{V}$
Thermal resistance	$R_{th(j-a)}$	—	400	—	°C/W	Polyimide board ²

Notes 1. Per one device

Notes 2. Polyimide board



Main Characteristic

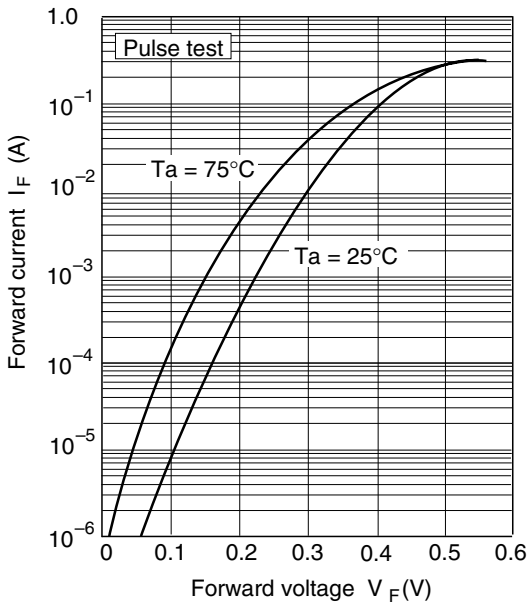


Fig.1 Forward current Vs. Forward voltage

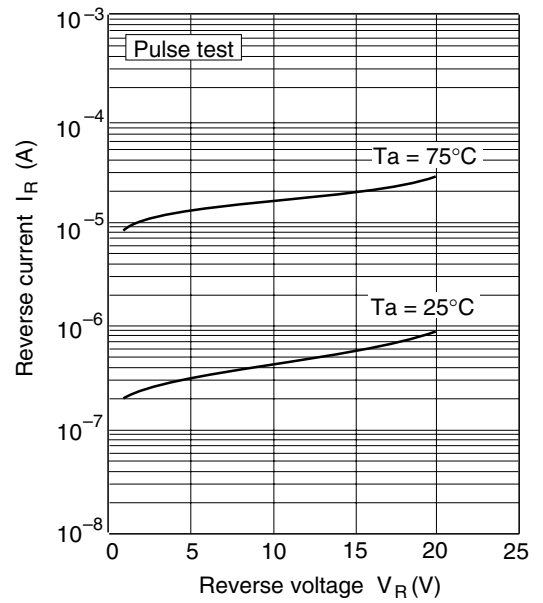


Fig.2 Reverse current Vs. Reverse voltage

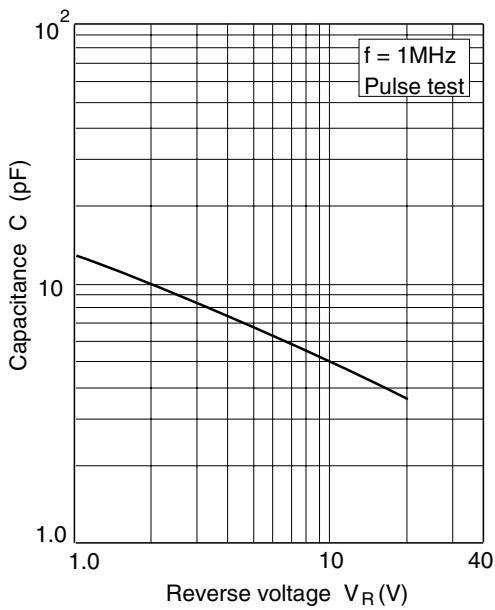


Fig.3 Capacitance Vs. Reverse voltage

Main Characteristic

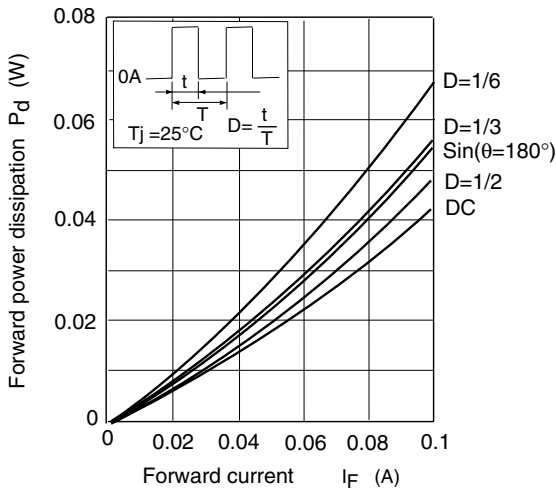


Fig4. Forward power dissipation Vs. Forward current

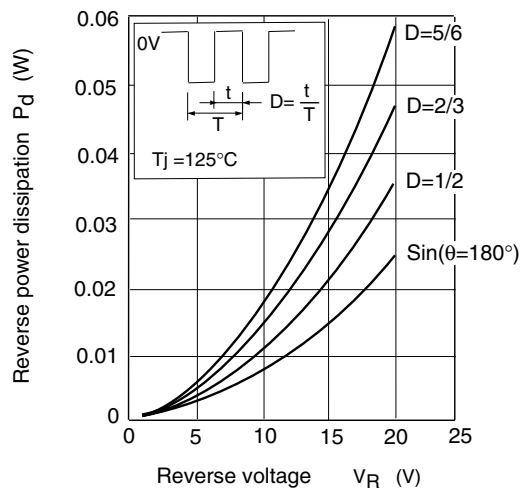


Fig5. Reverse power dissipation Vs. Reverse voltage

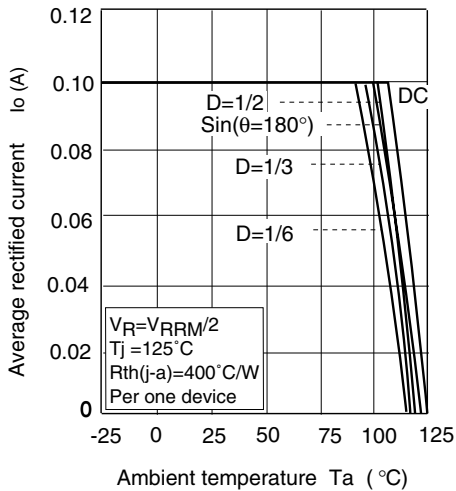


Fig.6 Average rectified current Vs. Ambient temperature

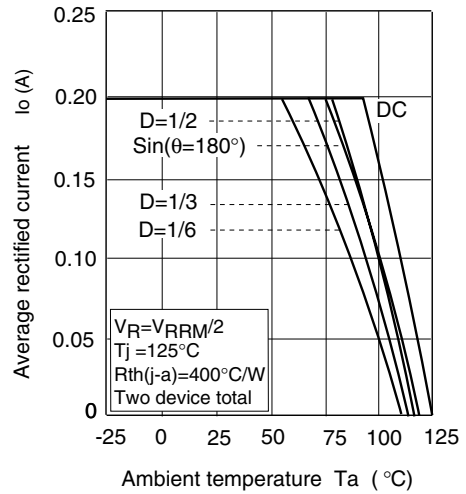
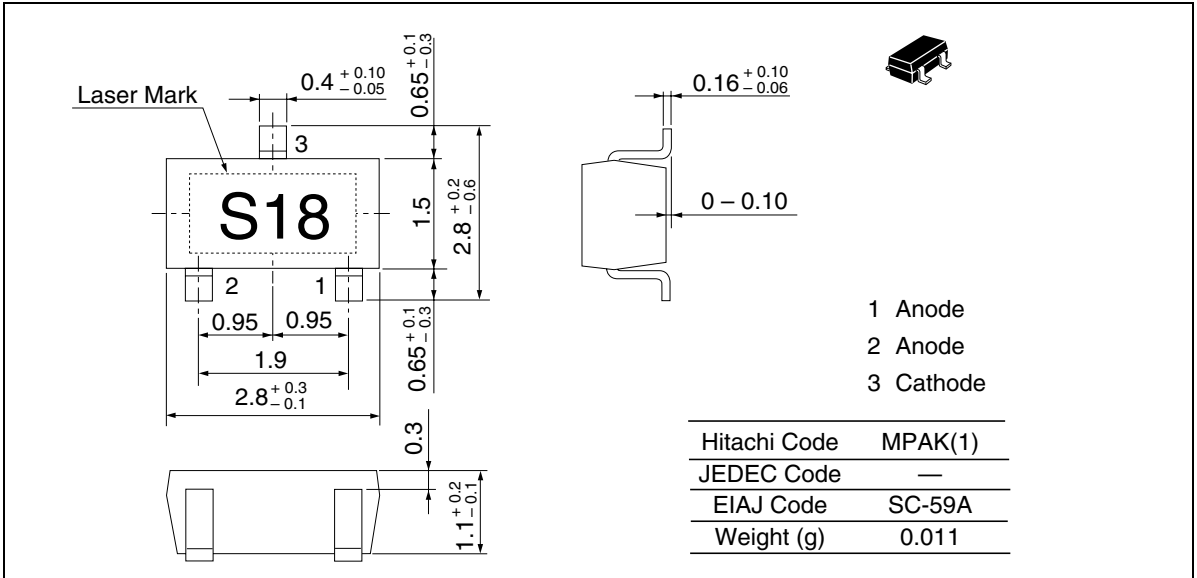


Fig.7 Average rectified current Vs. Ambient temperature

Package Dimensions

Unit : mm



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